

Information for Lot 9 of ErP (Ecodesign)

Model: SYS-2029GP-TR / SYS-2028GR-TR / SYS-2028GR-TRT

This appendix addresses European Union (EU) Eco-design requirements for servers and storage products. All data and ratings within this addendum are in reference only to the Supermicro product(s) in the manual. The below information corresponds to requirements laid down in Annex II of the commission regulation 2019/424.

- 3(1)(a): See Section 1.1 of the system manual for the product type.
- 3(1)(b): See the title page and preface of the system manual for the trademark and manufacturer's address.
- 3(1)(c): See title page for product model number(s).
- 3(1)(d): See serial number on the physical system to determine the year of manufacture.
- 3(1)(e-j): **PSU efficiency and power factor value (Table) (from 80 Plus report)**

PSU Model #: PWS-2K03P-1R Watts: 2000	PSU Efficiency				Power Factor
	10 %	20 %	50 %	100 %	
% of rated load					50 %
Single output (AC-DC)	91.46%	93.40%	94.55 %	92.02 %	1.00

System (EUT) efficiency in Idle State power (Table)

Representative Configurations	Measured Idle State Power (W)	Calculated Idle Power Allowance (W)
High-end performance configuration	419.4	396.51
Typical Configuration	N/A	N/A
Low-end performance configuration	165.7	294.71

System (EUT) efficiency in Active State power (Table)

Representative Configurations	Active State Efficiency Score (Effserver)	Minimum Active State Efficiency
High-end performance configuration	26.4	9.5
Typical Configuration	N/A	
Low-end performance configuration	21.1	

3(1)(k): The operating condition class is **A2**.

Operating	Dry bulb temp °C		Humidity range, non-condensing		Max dew	Maximum rate of
	Allowable	Recommended	Allowable range	Recommended		
A1	15- 32	18-27	– 12 °C Dew Point (DP) and 8 % relative humidity (RH) to	– 9 °C DP to 15 °C DP and 60 %	17	5/20
A2	10-35	18-27	– 12 °C DP and 8 % RH to 21 °C DP and	Same as A1	21	5/20
A3	5-40	18-27	– 12 °C DP and 8 % RH to 24 °C DP and	Same as A1	24	5/20
A4	5-45	18-27	– 12 °C DP and 8 % RH to 24 °C DP and	Same as A1	24	5/20

3(1)(l): The idle state power at the higher boundary temperature of the operating conditions class: 419.4 Watts.

3(1)(m): The active state efficiency and performance is a minimum of 21.1.

3(1)(n): There are two methods by which a user can securely delete data from this system. The user performing secure data deletion should be an IT professional.

The first is with a Unified Extensible Firmware Interface (UEFI) shell utility. This utility works on X10/X11/H11/H12/M11 motherboard series with onboard SATA/NVMe devices. Any user may access and download this utility through following link:
https://www.supermicro.com/about/policies/disclaimer.cfm?url=/wftp/utility/Lot9_Secure_Data_Deletion_UTILITY/

Download the shell utility package and extract it to a USB flash drive, then plug the drive into the server for which secure data deletion is necessary. Then turn the system on. Navigate to the BIOS setup menu, then place the server system into the UEFI shell environment. Follow the instructions in the README file to invoke the utility and complete the deletion.

The second method is through the secure data deletion tool provided by the original manufacturer of the hard drive. This should be used in a scenario where the shell utility is not applicable. Each manufacturer should have the tool available on their website. If needed, please look on the hard drive label for the name of the manufacturer and model information.

3(1)(o): List of recommended combinations of blade servers with chassis: N/A.

3(1)(p): List of all current SKUs within this product family: N/A.

3(3)(a): There is no use of cobalt in batteries in this product.

The indicative weight range of Neodymium in the HDD is 0.0 if manufactured by Western Digital, and is between 5-25 grams if manufactured by Seagate.

3(3)(b): Please see the disassembly instructions on the next page.

Illustrated Disassembly Instructions

Model: SYS-2029GP-TR / SYS-2028GR-TR / SYS-2028GR-TRT

Please note: All the illustrations in the below disassembly instructions are for demonstration only. Components shown here may not match exactly with the components in your system.

CAUTION: Always power off the system and unplug the power cord(s) first before disassembling the system!

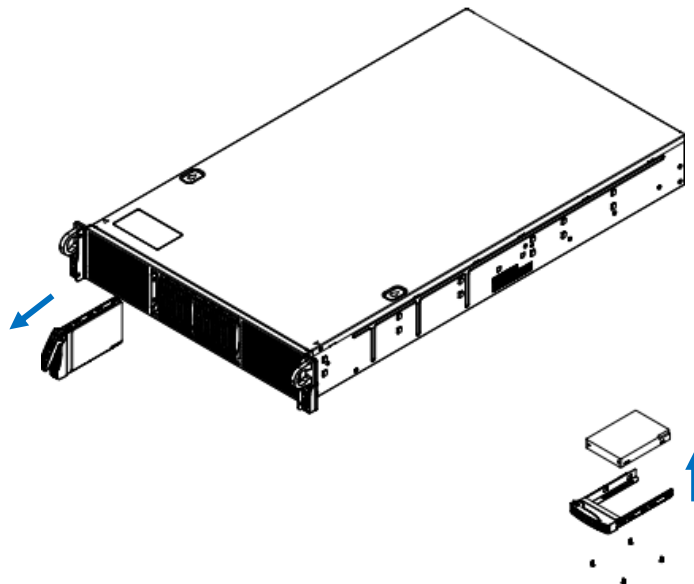
1. Data Storage Devices

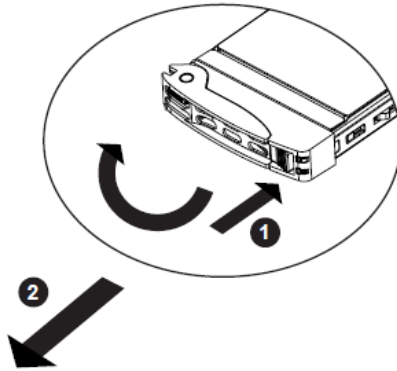
Type and number of fastenings: One (1) latch and four (4) screws.

Tools required: Screwdriver with PH2 bit.

Procedure:

1. Push the release button on the carrier. This extends the carrier handle.
2. Swing the handle fully out.
3. Grasp the handle and use it to pull the drive carrier out of its bay.
4. Remove the screws that secure the hard drive to the carrier and separate the hard drive from the carrier.





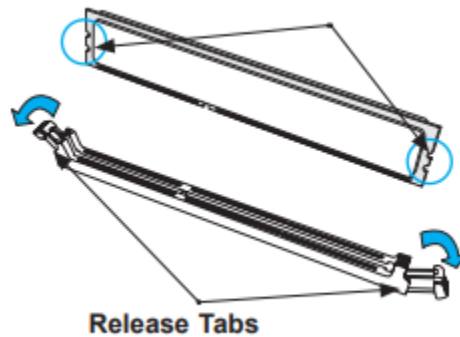
2. Memory

Type and number of fastenings: Two (2) latches per memory module.

Tools required: None.

Procedure:

Press both release tabs on the ends of the DIMM module to unlock. Once the DIMM module is loosened, remove it from the memory slot.



3. Processor (LGA-3647 Socket)

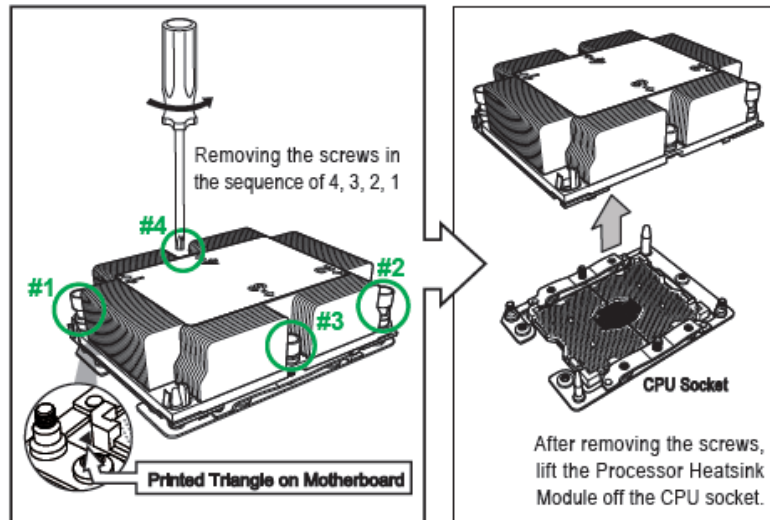
Type and number of fastenings: Four (4) T30 Torx screws.

Tools required: Screwdriver with T30 Torx bit.

Procedure:

Before removing the processor heatsink module (PHM), unplug power cord from the power outlet.

1. Using a T30 Torx-bit screwdriver, turn the screws on the PHM counterclockwise to loosen them from the socket, starting with the screw marked #4, in the sequence of 4, 3, 2, 1.
2. After all of the four screws are removed, wiggle the PHM gently and pull it up to remove it from the socket.



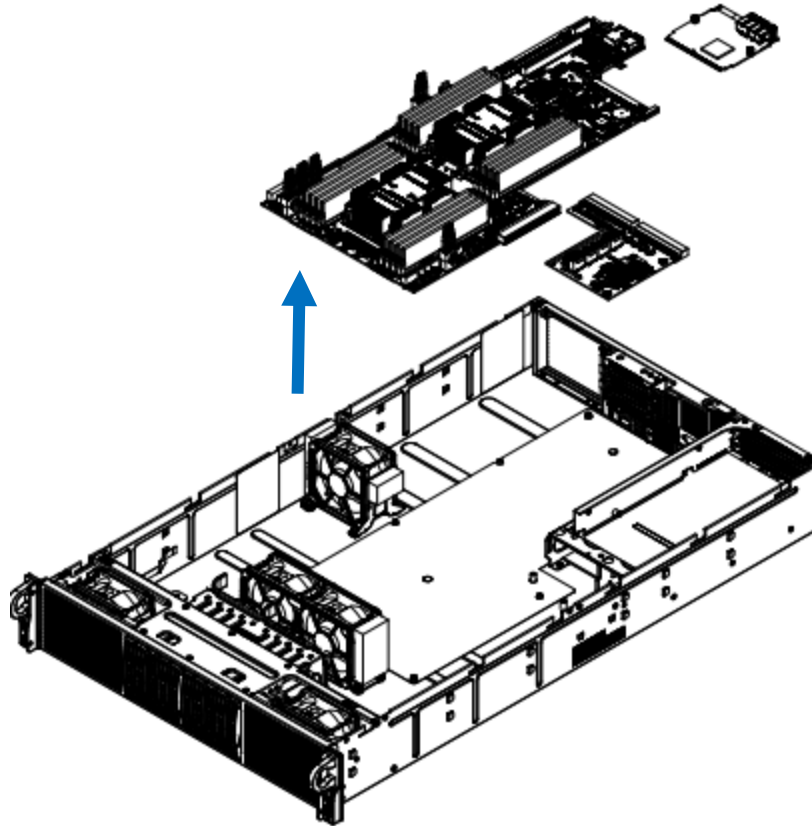
4. Motherboard and Power Distribution Board

Type and number of fastenings: Several screws dispersed around the printed circuit board.

Tools required: Screwdriver with PH2 bit.

Procedure:

1. Remove the screws that attach the motherboard and power distribution board to the chassis.
2. Disconnect any attached cables from boards.
3. Remove the power distribution board from the chassis.
4. Remove the motherboard by lifting it directly up and out of chassis.



5. Expansion Cards and GPUs

Type and number of fastenings: One (1) or more screws.

Tools required: Screwdriver with PH2 bit.

Procedure:

Remove full-height GPU cards on the front-view left (Slot 1) and right (Slot 2) riser assemblies:

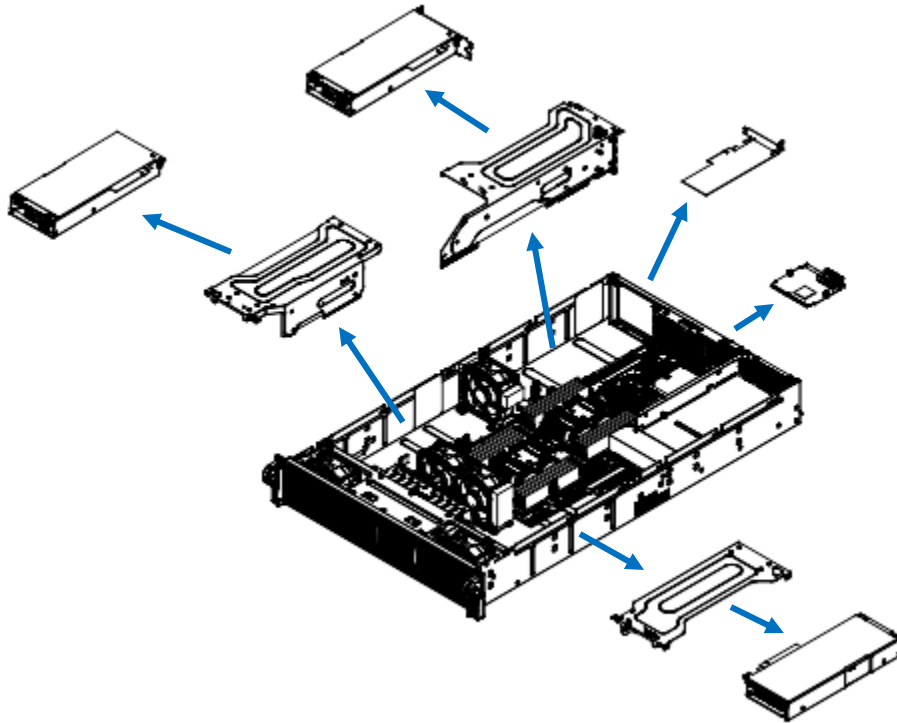
1. Remove the riser assembly bracket by unscrewing only those screws indicated by the screwdriver icon.
2. Unscrew the screw(s) holding the GPU bracket(s) to the riser assembly.
3. Remove the GPU card(s) if installed.
4. Slide the GPU(s) away from the slot on the riser assembly.

Remove full-height expansion card or GPU cards on the rear-view right-side (Slots 3, 4) and the low-profile (LP) add-on card (AOC) (Slot 5):

1. Remove the right-side riser assembly bracket by unscrewing only those screws indicated by the screwdriver icon.
2. Unscrew the single screw(s) holding the AOC/GPU I/O bracket(s) to the riser assembly.
3. Remove the full-height and low-profile AOCs if installed.
4. Slide the expansion card(s) away from the slot on the riser assembly.

Remove SIOM expansion card:

1. Unscrew the screws holding the SIOM to the chassis.
2. Remove the SIOM module and any supporting I/O brackets from the rear of the chassis.



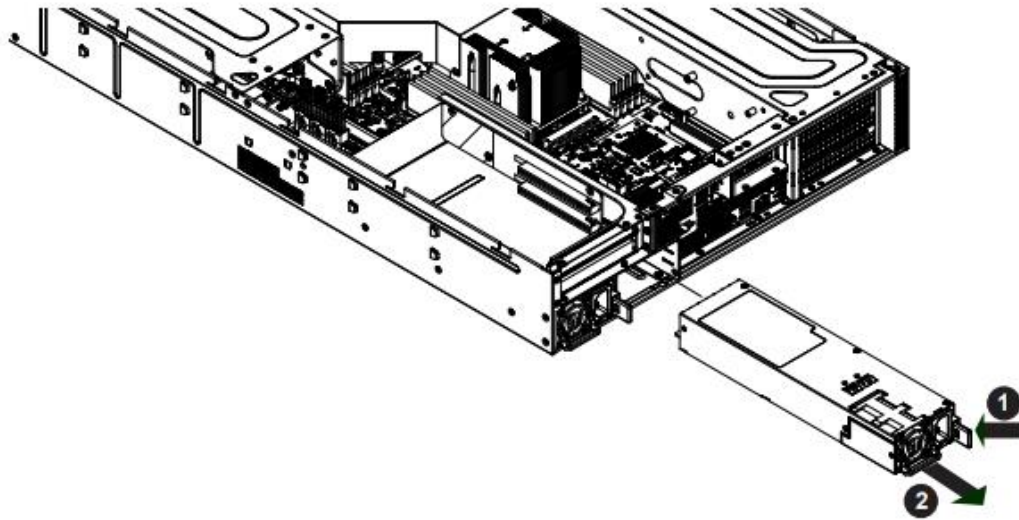
6. Power Supply Module

Type and number of fastenings: One (1) release tab per module.

Tools required: None.

Procedure:

1. Power down the system.
2. Push the release tab on the front of the power supply.
3. Lift the handle of the power supply.
4. Pull the power supply out of the power supply bay.
5. Do the same for second power supply, if installed.



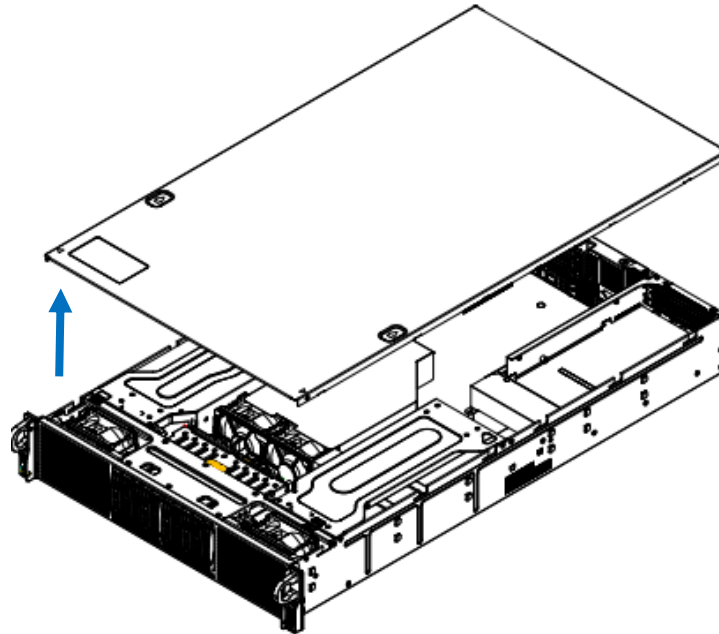
7. Chassis Cover

Type and number of fastenings: Three (3) screws.

Tools required: Screwdriver with PH2 bit.

Procedure:

1. Remove the screws securing the cover to the chassis.
2. Pull the cover toward the end of the chassis and off.



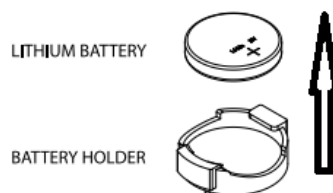
8. Batteries

Type and number of fastenings: One (1) latch.

Tools required: None.

Procedure:

1. Locate the coin cell battery on the motherboard.
2. Push aside the small clamp that covers the edge of the battery. When the battery is released, lift it out of the holder.



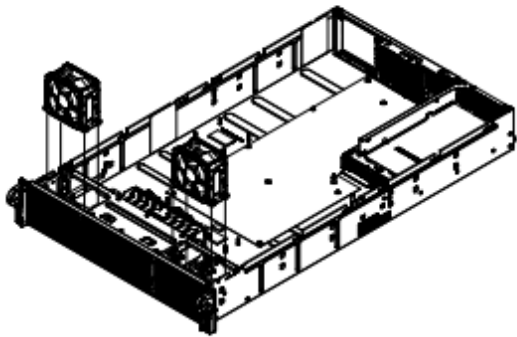
9. Fans

Type and number of fastenings: One (1) set of wiring cables and fan housing per internal fan.

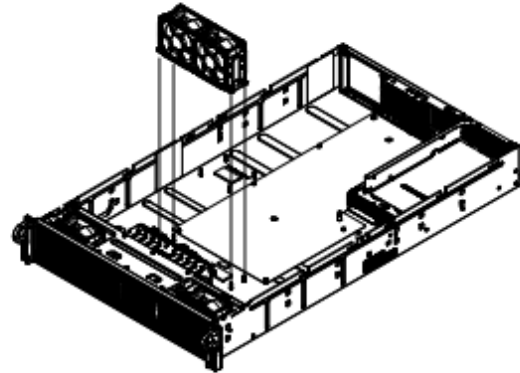
Tools required: None.

Procedure:

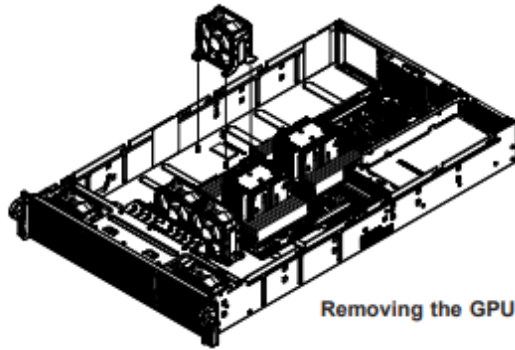
1. Remove the internal fan wiring from the fan header on the motherboard.
2. Remove the four pins securing the fan to the fan housing.
3. Lift the fan from the fan housing and out of the chassis.



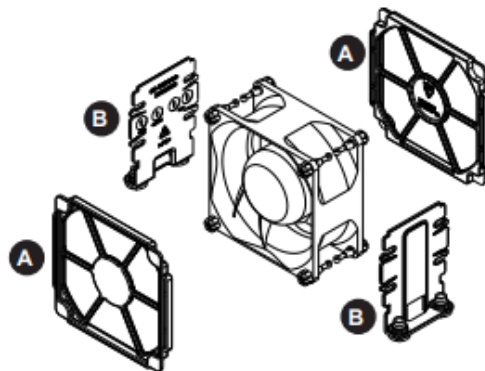
Removing the Front Fans

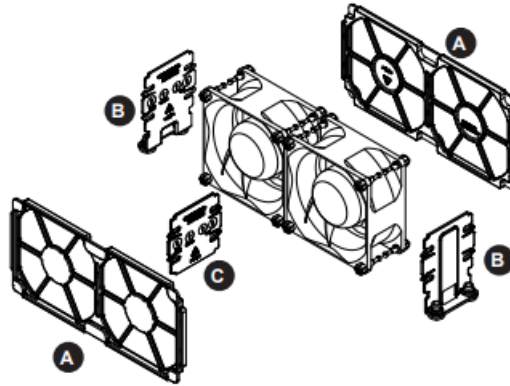


Removing the Mid Fans



Removing the GPU Fan





10. Air Shroud

Type and number of fastenings: None.

Tools required: None.

Procedure:

Lift the plastic air shroud up and away from the motherboard.

